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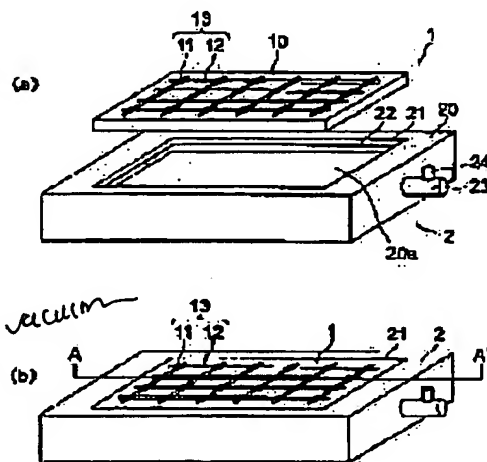
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(54) MANUFACTURING JIG AND MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To stably hold flat a manufacturing jig of a semiconductor device which can hold a board such as a flexible tape, etc., and the manufacturing device of the semiconductor device which employs the jig.

SOLUTION: A manufacturing jig comprises a holding plate 1, which is integrally formed on the aperture 21 of a plate supporting table 2 having a hollow part 20a in it and the aperture 21 continuous with the hollow part 20a or fitted to aperture 21 with an O-ring therebetween and has a flat mounting board holding plane, attracting holes 11 which pierce through the holding plate 1 in the mounting board holding plane and an air suction means which sucks air, for instance air in the hollow part, through the suction holes 11 from the opposite side of the mounting board holding plane. The mounting board is put on the mounting board holding plane, so as to close the suction holes 11, the air in the hollow part is sucked by the suction means and the mounting board is sucked, held and fixed.



LEGAL STATUS

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